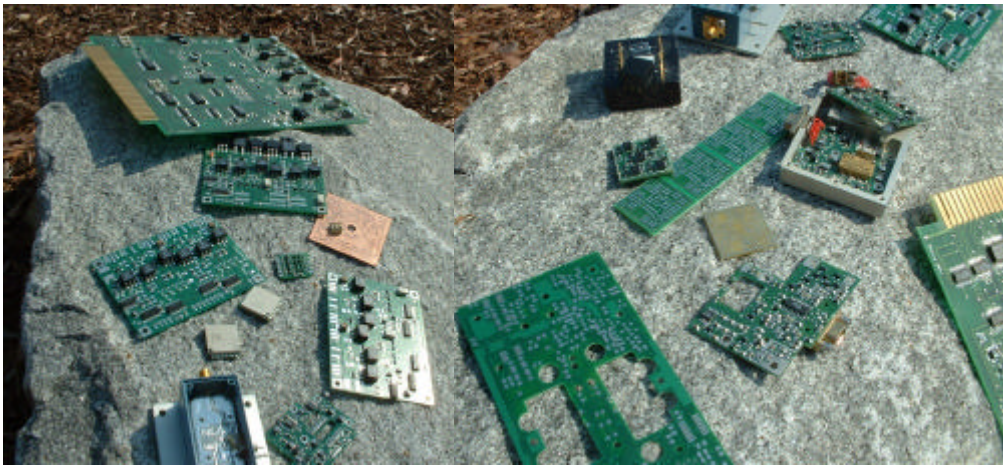


Don't take our Micro PCB's for Granite !

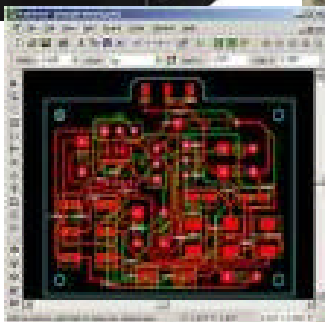


Since our start in 1986, Impellimax has always been about fulfilling our Customers' needs.

Most of the time, in the early days, that meant a **hermetic hybrid** was needed, and we have supplied untold thousands of those to numerous military and scientific programs. Even then, though, some applications were better served with tiny **PCB Assemblies**. So that is what Impellimax suggested, designed, and delivered, without any fuss or fanfare.

Now it's time for Fuss and Fanfare !

Impellimax can now convert your rough-idea circuit needs into **Drop-In Solutions**, with our start-to-finish micro SMD design and assembly line, in quick-turn speed and **without killer NRE's**.

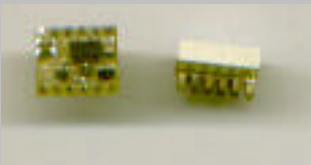


Let us start supplying your mini/micro PCB needs and then we'll let you . . .

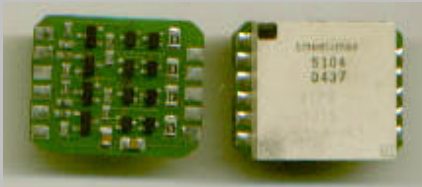
Take us for Granite.

- * **In-house circuit design, working from your block diagram and your customer specifications.**
- * **Utilize our 20 years of PIN Driver experience in your units.**
- * **Layout derating for airborne PCB assemblies, as applicable**
- * **Conformal coating IAW military and commercial specifications**
- * **Controlled impedance layouts for RF amplifiers, switches, etc.**
- * **In-house board edge routing, V-scoring, pocket cutting to fit your housing**
- * **Encapsulation as needed for pick-and-place, thermal conductivity, mechanical benefits**
- * **Chip-on-board (COB) capability when needed**
- * **In-house PCB layout, stencil generation, component placement, electrical test**
- * **High temperature RoHS – compliant solder and terminations available**

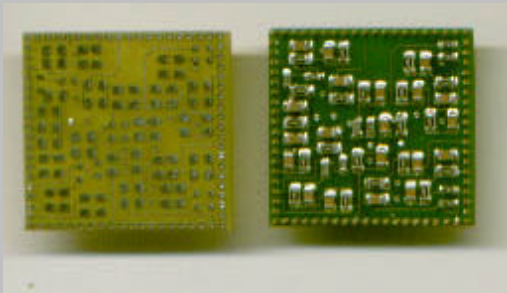
Some examples :



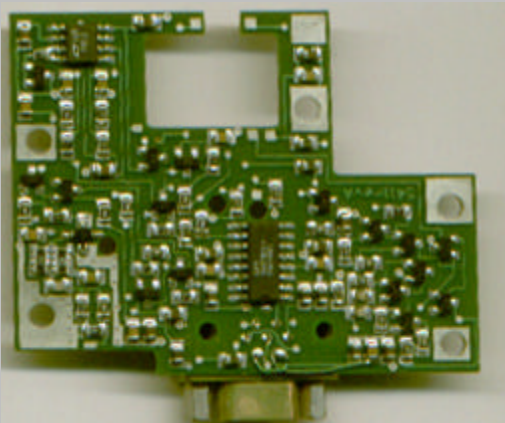
Ultra-mini PIN switch drivers. Encapsulated for easy pick and place. Only .35 inch by .25 inch footprint, low cost design.



Small 4 channel PIN driver. Chamfered corners allowed this design to maximize use of available floor space within the housing.



BGA footprint 5 channel, 10 output +250V PIN diode driver. Constructed with brass contact feet and high-temp solder to enable use as a BGA daughter board. Dual-sided assembly with airborne avionics compliant layout.



Multi-function drop-in subassembly with RF amplification, high-speed video pulse detection, and several PIN switch driver circuits in a user-friendly shaped layout. Backside is fully grounded for low loss and low-noise operation.